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NPN SILICON PHOTOTRANSISTOR LED LAMPS



Lead-Free Parts

LPT2020/A-PF-18

# DATA SHEET

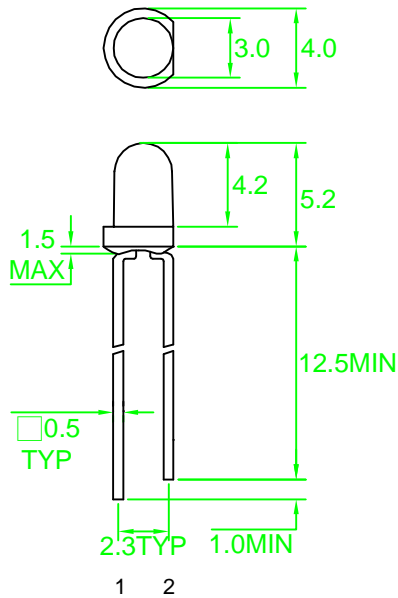
DOC. NO : QW0905-LPT2020/A-PF-18

REV. : A

DATE : 03 - Aug. - 2016



Package Dimension



1.EMITTER  
2.COLLECTOR

Features

- High illumination sensitivity
- Stable characteristics
- Spectrally and mechanically matched with IR emitter

Description

The LPT2020/A-PF-18 series are silicon nitride passivated NPN planar phototransistors with exceptionally stable characteristics and high illumination sensitivity the cases of LPT2020/A-PF-18 are encapsulated in water clear plastic T1 3/4 package individualt

Note:1.All dimension are in millimeter tolerance is  $\pm 0.25\text{mm}$  unless otherwise noted  
2.Specifications are subject to change without notice

• MAXIMUM RATINGS( $T_a=25^\circ\text{C}$ )

PARAMETER	MAXIMUM RATINGS	UNIT
Power Dissipation	100	mw
Collector-Emitter Voltage	30	V
Emitter-Collector Voltage	5	V
Operating Temperature	-50°C TO +100°C	
Storage Temperature	-50°C TO +100°C	

• ELECTRICAL CHARACTERISTICS( $T_a=25^\circ\text{C}$ )

PARAMETER	SYMBOL	Min.	Typ.	Max.	UNIT	TEST CONDITION
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	30			V	$I_c=1\text{mA}$ $E_e=0\text{mw}/\text{cm}^2$
Emitter-Collector Breakdown Voltage	$V_{(BR)ECO}$	5			V	$I_E=100\ \mu\text{A}$ $E_e=0\text{mw}/\text{cm}^2$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$			0.4	V	$I_c=0.5\text{mA}$ $E_e=20\text{mw}/\text{cm}^2$
Rise Time	$T_r$		5		$\mu\text{S}$	$V_{CE}=30\text{V}$ $I_C=800\ \mu\text{A}, R_L=1\text{K}\ \Omega$
Fall Time	$T_f$		5		$\mu\text{S}$	
Collector Dark Current	$I_{CEO}$			100	nA	$V_{CE}=10\text{V}$ $E_e=0\text{mw}/\text{cm}^2$
On State Collector Current	$I_p(on)$	2		4	mA	$V_{CE}=5\text{v}$ $E_e=1\text{mw}/\text{cm}^2$ $\lambda P=940\text{nm}$
		4		8	mA	
		8		16	mA	
		16		32	mA	

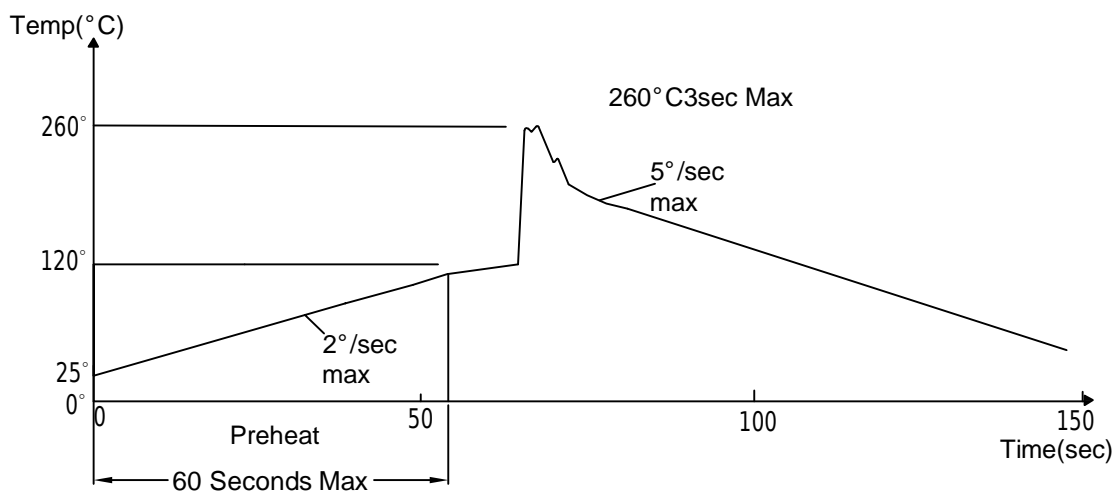
**Soldering Condition(Pb-Free)**

## 1.Iron:

Soldering Iron:30W Max  
Temperature 350° C Max  
Soldering Time:3 Seconds Max(One time only)  
Distance:2mm Min(From solder joint to body)

## 2.Wave Soldering Profile

Dip Soldering  
Preheat: 120° C Max  
Preheat time: 60seconds Max  
Ramp-up  
2° C/sec(max)  
Ramp-Down:-5° C/sec(max)  
Solder Bath:260° C Max  
Dipping Time:3 seconds Max  
Distance:2mm Min(From solder joint to body)

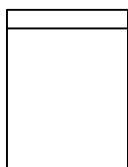


Note: 1.Wave solder should not be made more than one time.  
2.You can just only select one of the soldering conditions as above.

### Reliability Test:

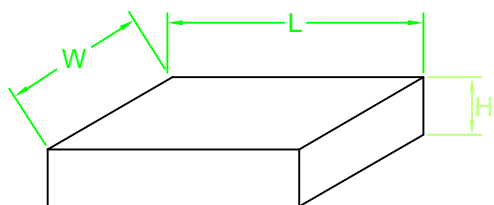
Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=85°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65°C±5°C 2.RH=90%~95% 3.t=240hrs±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105°C±5°C&-40°C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260°C±5°C 2.Dwell time= 10±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=245°C±5°C 2.Dwell time=5±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2

1. 1000 PCS / BAG



2. 8 BAG / INNER BOX

SIZE : L X W X H 33cm X 18cm X 9cm



3. 12 INNER BOXES / CARTON

SIZE : L X W X H 58.5cm X 34cm X 34cm

